PRELIMINARY



CGH27060F

60 W, 2300-2900 MHz, 28V, GaN HEMT for WiMAX

Cree's CGH27060F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH27060F ideal for 2.3-2.9GHz WiMAX and BWA amplifier applications. The transistor is supplied in a ceramic/metal flange package.



Package Type: 440193 PN: CGH27060F

Typical Performance Over 2.3-2.6GHz ($T_c = 25$ °C) of Demonstration Amplifier

| Parameter | 2.3 GHz | 2.4 GHz | 2.5 GHz | 2.6 GHz | Units |
|---------------------------|---------|---------|---------|---------|-------|
| Small Signal Gain | 13.5 | 13.3 | 13.0 | 12.9 | dB |
| EVM @ 39 dBm | 2.1 | 1.9 | 1.9 | 2.2 | % |
| Drain Efficiency @ 39 dBm | 24.2 | 23.8 | 22.5 | 22.3 | % |
| Input Return Loss | 9.8 | 16.0 | 7.7 | 5.9 | dB |

Note:

Measured in the CGH27060F-TB amplifier circuit, under 802.16-2004 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3.

Features

- 2.3 2.9 GHz Operation
- >13 dB Small Signal Gain
- 2.0 % EVM at 8 W P_{OUT}
- 23 % Efficiency at 8 W P_{OUT}
- 2.7°C/W Typical thermal resistance under 8.0 W P_{AVE} OFDM
- WiMAX Fixed Access 802.16-2004 OFDM
- WiMAX Mobile Access 802.16e OFDMA





Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

| Parameter | Symbol | Rating | Units |
|---|-----------------------------|-----------|-------|
| Drain-Source Voltage | $V_{\scriptscriptstyleDSS}$ | 84 | Volts |
| Gate-to-Source Voltage | V_{GS} | -10, +2 | Volts |
| Storage Temperature | T _{stg} | -55, +150 | °C |
| Operating Junction Temperature | т, | 175 | °C |
| Soldering Temperature | T_s | 245 | °C |
| Thermal Resistance, Junction to Case ¹ | $R_{_{\theta JC}}$ | 2.7 | °C/W |

Note:

¹Measured for the CGH27060F at 8 W P_{DISS}

Electrical Characteristics ($T_c = 25$ °C)

| Characteristics | Symbol | Min. | Тур. | Max. | Units | Conditions |
|--|--------------------------|---------------|-------------|------|-------|---|
| DC Characteristics ⁴ | | | | | | |
| Gate Threshold Voltage | $V_{\rm GS(th)}$ | -3.6 | -2.5 | - | VDC | V_{DS} = 10 V, I_{D} = 14.4 mA |
| Gate Quiescent Voltage | $V_{GS(\mathtt{Q})}$ | - | -2.6 | - | VDC | $V_{DS} = 28 \text{ V, } I_{D} = 240 \text{ mA}$ |
| Saturated Drain Current | $I_{	extsf{DS}}$ | 9.6 | 10.4 | - | А | $V_{DS} = 6.0 \text{ V}, V_{GS} = 2 \text{ V}$ |
| Drain-Source Breakdown Voltage | $V_{\rm BR}$ | 84 | 100 | - | VDC | $V_{GS} = -8 \text{ V, } I_D = 14.4 \text{ mA}$ |
| Case Operating Temperature | T _c | -10 | - | +105 | °C | Under 8 W P _{AVE} |
| Screw Torque | Т | - | - | 80 | in-oz | Reference 440193 Package Revision 1 |
| RF Characteristics ^{2,3} (T _c = 25 °C, F | _o = 2.5 GHz u | ınless otherw | vise noted) | | | |
| Small Signal Gain | G_{ss} | - | 13.0 | - | dB | V_{DD} = 28 V, I_{DQ} = 240 mA |
| Drain Efficiency ¹ | η | - | 22.5 | - | % | V_{DD} = 28 V, I_{DQ} = 240 mA, P_{AVE} = 8 W |
| Back-Off Error Vector Magnitude | EVM ₁ | - | 2.5 | - | % | $V_{DD} = 28 \text{ V, I}_{DQ} = 240 \text{ mA,}$ $P_{AVE} = 24 \text{ dBm}$ |
| Error Vector Magnitude | EVM ₂ | - | 2.0 | - | | V_{DD} = 28 V, I_{DQ} = 240 mA, P_{AVE} = 8 W |
| Output Mismatch Stress | VSWR | - | TBD | - | Ψ | No damage at all phase angles, $V_{\rm DD}$ = 28 V, $I_{\rm DQ}$ = 240 mA |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{GS} | - | 19.3 | - | pF | $V_{DS} = 28 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$ |
| Output Capacitance | C _{DS} | - | 4.6 | - | pF | $V_{DS} = 28 \text{ V}, V_{gs} = -8 \text{ V}, f = 1 \text{ MHz}$ |
| Feedback Capacitance | C_{GD} | - | 1.7 | - | pF | $V_{DS} = 28 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$ |

Notes:

 $^{^{1}}$ Drain Efficiency = P_{out} / P_{DC}

² Under 802.16-2004 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3.

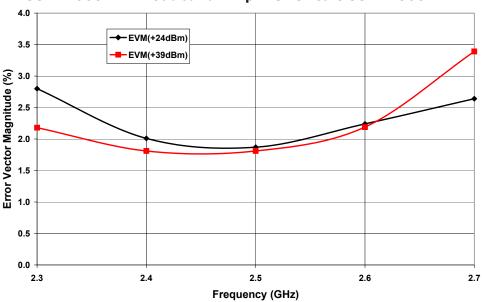
³ Measured in the CGH27060F-TB test fixture.

⁴ Measured on wafer prior to packaging.



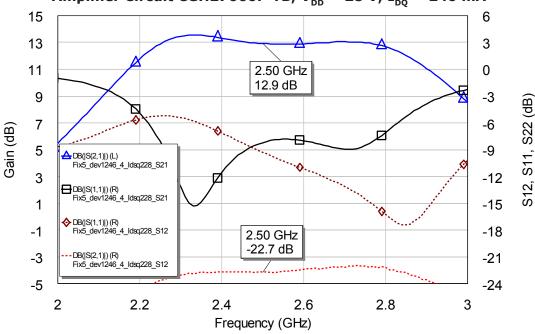
Typical WiMAX Performance

Typical EVM at 24 dBm and 39 dBm vs Frequency of CGH27060F in Broadband Amplifier Circuit CGH27060F-TB



Note: Under 802.16-2004 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3.

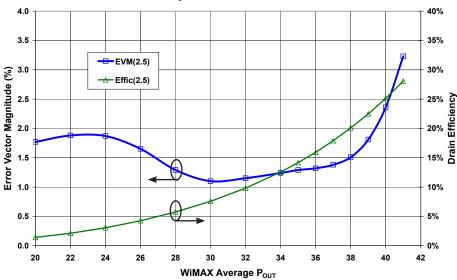
Gain and Return Loss vs Frequency of CGH27060F in Broadband Amplifier Circuit CGH27060F-TB, $V_{\rm DD}$ = 28 V, $I_{\rm DO}$ = 240 mA





Typical WiMAX Performance

EVM vs P_{OUT} at 2.5 GHz of CGH27060F in Broadband Amplifier Circuit CGH27060F-TB

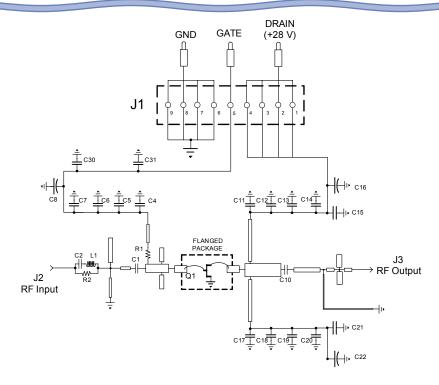


Note:

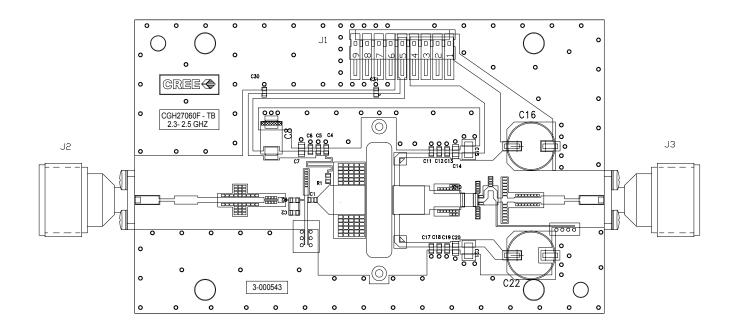
Under 802.16-2004 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3.



CGH27060F-TB Demonstration Amplifier Circuit Schematic



CGH27060F-TB Demonstration Amplifier Circuit Outline



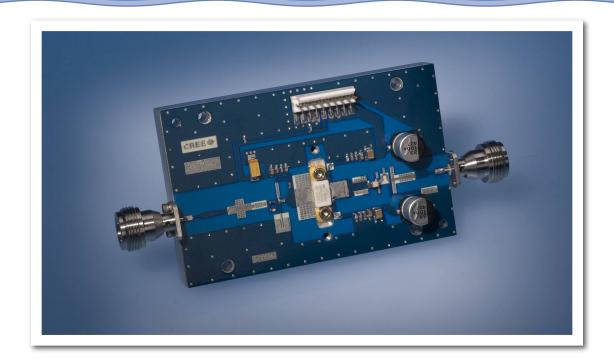


CGH27060F-TB Demonstration Amplifier Circuit Bill of Materials

| Designator | Description | Qty |
|--------------------|--|-----|
| R1 | RES, 1/16W, 0603, 1%, 22 OHMS | 1 |
| R2 | RES, 1/16W, 0603, 1%, 100 OHMS | 1 |
| C6,C13,C19 | CAP, 470PF, 10%,100V, 0603 | 3 |
| C16,C22 | CAP, 33 UF, 20%, G CASE | 1 |
| C15,C21 | CAP, 1.0UF, 100V, 10%, X7R, 1210 | 1 |
| C8 | CAP 10UF 16V TANTALUM | 1 |
| C10 | CAP, 8.2pF, +/-5%, 100B | 1 |
| C1 | CAP, 0.9pF, +/-0.05pF, 0603 | 1 |
| C2 | CAP, 2.2pF, +/-0.1pF, 0603 | 1 |
| C4,C11,C17 | CAP, 10.0pF,+/-5%, 0603 | 3 |
| C5,C12,C18,C30,C31 | CAP, 82pF, +/-5%, 0603 | 5 |
| C7,C14,C20 | CAP,33000PF, 0805,100V, X7R | 3 |
| L1 | It is a trace on the PCB and does not require a component. | 1 |
| J2,J3 | CONN SMA STR PANEL JACK RECP | 1 |
| J1 | HEADER RT>PLZ .1CEN LK 9POS | 1 |
| Q1 | CGH27060F | 1 |

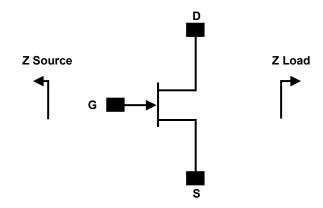
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CGH27060F-TB Demonstration Amplifier Circuit





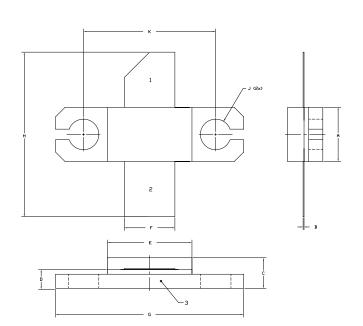
Source and Load Impedances



| Frequency (MHz) | Z Source | Z Load |
|-----------------|------------|-------------|
| 2300 | 3.3 - j7.0 | 11.2 - j7.8 |
| 2400 | 4.0 - j7.0 | 9.9 - j8.0 |
| 2500 | 4.1 - j7.5 | 8.4 - j8.1 |
| 2600 | 3.6 - j7.7 | 7.3 - j7.8 |
| 2700 | 2.9 - j7.3 | 6.1 - j7.3 |

Note¹: V_{DD} = 28V, I_{DQ} = 240mA. In the 440193 package. Note²: Impedances are extracted from the CGH27060F-TB demonstration circuit and are not source and load pull data derived from the transistor.

Product Dimensions CGH27060F (Package Type — 440193)



1. DIMENSIONING AND TOLERANICING PER ANSI Y14.5M, 1982.

3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020' BEYOND EDGE OF LID.

4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008' IN ANY DIRECTION.

5. ALL PLATED SURFACES ARE NI/AU

| | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.225 | 0.235 | 5.72 | 5.97 |
| В | 0.004 | 0.006 | 0.10 | 0.15 |
| С | 0.125 | 0.135 | 3.18 | 3.43 |
| D | 0.077 | 0.087 | 1.96 | 2.21 |
| E | 0.355 | 0.365 | 9.02 | 9.27 |
| F | 0.210 | 0.220 | 5.33 | 5.59 |
| G | 0.795 | 0.805 | 20.19 | 20.45 |
| Н | 0.670 | 0.730 | 17.02 | 18.54 |
| J | ø .130 | | 3.30 | |
| k | 0.562 | | 14. | 28 |

PIN 1. GATE PIN 2. DRAIN PIN 3. SOURCE



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